

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(multi adj flip adj chip adj module).clm. and (leadframe adj3 pad)".clm" and (outer adj lead). clm. and (integrated adj circuit).clm. and (bond adj wire).clm. and (power adj mosfet).clm. and (molded adj resin).clm.	US-PGPUB	OR	ON	2006/08/14 16:27
L2	1	(multi adj flip adj chip adj module).clm. and (leadframe adj3 pad)".clm" and (outer adj lead). clm. and (integrated adj circuit).clm. and (power adj mosfet).clm. and (molded adj resin). clm.	US-PGPUB	OR	ON	2006/08/14 16:27

Search History Printout

10/803464

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	4144	257/666.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:33
L9	498	257/673.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:33
L10	2439	257/676.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:33
L11	2377	257/723.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:33
L12	1785	257/724.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:33
L13	2884	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:33
L14	11991	L8 or L9 or L10 or L11 or L12 or L13	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:33
L15	11991	L14	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:37
L16	6159	L8 or L9 or L10	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:37
L17	6159	L16	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:38

EAST Search History

L18	5832	L14 not L16	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:41
L19	5832	L18	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/08/14 16:41